

IN THE CLAIMS:

Cancel claims 3, 5, 14, 16, 24, 26, 34, 36, 46, 48, 52, 54, 59, 61, 63, 68, 69, and 70.

Please amend the claims as follows:

1. (Currently Amended) A method of attaching a wafer having bumps on a surface thereof, comprising:
attaching a tape having an adhesive and a backing on at least a portion of said surface having bumps thereon of said wafer;
conforming at least a portion of said adhesive of said tape to said bumps to form a substantially planar surface on said backing of said tape;
providing a wafer mount having a suction surface; and
applying a suction force to said backing of said tape.

2. (Original) The method of claim 1, further comprising:
removing wafer material from a back surface of said wafer.

3. (Canceled)

4. (Previously Presented) The method of claim 3, wherein said applying said suction force to said backing of said tape comprises applying a suction force to said substantially planar surface of said backing.

5. (Canceled)

6. (Original) The method of claim 1, wherein said applying a suction force to said backing of said tape includes abutting said backing to said suction surface of said wafer mount.

7. (Original) The method of claim 1, wherein said wafer comprises a wafer having a thickness of at least about 12 mils.

8. (Previously Presented) The method of claim 2, wherein said removing comprises thinning said wafer to a thickness in the range of between about 6 mils and about 12 mils.

9. (Original) The method of claim 2, wherein said removing comprises thinning said wafer to one of about 6 mils thickness and less than about 6 mils thickness.

10. (Original) The method of claim 2, wherein said removing comprises grinding said back surface of said wafer.

11. (Original) The method of claim 2, wherein said removing comprises thinning said wafer by chemical-mechanical polishing said back surface of said wafer.

12. (Currently Amended) A method of holding a wafer having bumps on at least a portion of a surface thereof, comprising:
applying an adhesive to said surface of said wafer;
attaching a backing to at least a portion of said adhesive;
conforming at least a portion of said adhesive of said tape to said bumps to form a substantially planar surface on said backing of said tape;
providing a wafer mount having a suction surface; and
holding said backing to said suction surface of said wafer mount using a suction force.

13. (Original) The method of claim 12, further comprising:
removing wafer material from another surface of said wafer.

14. (Canceled)

15. (Previously Presented) The method of claim 14, wherein said holding said backing to said suction surface of said wafer mount comprises applying said suction force to said substantially planar surface of said backing.

16. (Canceled)

17. (Original) The method of claim 12, wherein said holding said backing to said suction surface of said wafer mount comprises abutting at least a portion of said backing to said suction surface of said wafer mount.

18. (Original) The method of claim 12, wherein said wafer comprises a wafer having a thickness of at least about 12 mils.

19. (Previously Presented) The method of claim 13, wherein said removing comprises thinning said wafer to a thickness in the range of about 6 mils to about 12 mils.

20. (Original) The method of claim 13, wherein said removing comprises thinning said wafer to one of a thickness of about 6 mils and a thickness of about less than 6 mils.

21. (Previously Presented) The method of claim 13, wherein said removing comprises grinding said another surface of said wafer.

22. (Previously Presented) The method of claim 13, wherein said removing comprises thinning said wafer by chemical-mechanical polishing said another surface of said wafer.

23. (Currently Amended) A method of thinning a wafer comprising:
providing a wafer having bumps on at least a portion of a surface thereof;
attaching an adhesive having a backing to at least a portion of said at least a portion of said
surface of said wafer;
conforming at least a portion of said adhesive of said tape to said bumps to form a substantially
planar surface on said backing of said tape;

providing a wafer mount having a suction surface;
attaching said backing of said adhesive to at least a portion of said suction surface of said wafer
mount using a suction force; and
removing wafer material from another surface of said wafer.

24. (Canceled)

25. (Original) The method of claim 24, wherein said attaching said backing to at least
a portion of said suction surface of said wafer mount comprises applying said suction force to
said substantially planar surface of said backing.

26. (Canceled)

27. (Previously Presented) The method of claim 23, wherein said attaching said
backing to at least a portion of said suction surface of said wafer mount comprises abutting at
least a portion of said backing to said at least a portion of said suction surface and wherein said
suction force attaches said wafer to said wafer mount.

28. (Original) The method of claim 23, wherein said wafer comprises a wafer having
a thickness of at least about 12 mils.

29. (Previously Presented) The method of claim 24, wherein said removing comprises thinning said wafer to a thickness in the range of between about 6 mils and about 12 mils.

30. (Original) The method of claim 23, wherein said removing comprises thinning said wafer to one of about 6 mils and less than about 6 mils.

31. (Previously Presented) The method of claim 23, wherein said removing comprises grinding said another surface of said wafer.

32. (Previously Presented) The method of claim 23, wherein said removing comprises thinning said wafer by chemical-mechanical polishing said another surface of said wafer.

33. (Currently Amended) A method of fabricating a wafer having a front surface having bumps thereon and a back surface, comprising:
applying an adhesive having a backing onto at least a portion of said bumps ~~and said front surface of said wafer;~~
conforming at least a portion of said adhesive of said tape to said bumps to form a substantially planar surface on said backing of said tape;
providing a wafer mount having a suction surface;
attaching at least a portion of said backing to at least a portion of said suction surface of said wafer mount using a suction force; and
removing wafer material from said back surface of said wafer.

34. (Canceled)

35. (Previously Presented) The method of claim 34, wherein said attaching at least a portion of said backing to at least a portion of said suction surface of said wafer mount comprises

applying said suction force to at least a portion of said substantially planar surface of said backing.

36. (Canceled)

37. (Previously Presented) The method of claim 33, wherein said attaching at least a portion of said backing to at least a portion of said suction surface of said wafer mount comprises abutting at least a portion of said backing to said suction surface and wherein said suction force to attach said wafer to said wafer mount.

38. (Original) The method of claim 33, wherein said wafer comprises a wafer having a thickness of at least about 12 mils.

39. (Original) The method of claim 33, wherein said removing comprises thinning said wafer to a thickness in the range of between about 6 mils and about 12 mils.

40. (Original) The method of claim 33, wherein said removing comprises thinning said wafer to a thickness of one of about 6 mils and less than about 6 mils.

41. (Previously Presented) The method of claim 33, wherein said removing comprises grinding said back surface of said wafer.

42. (Previously Presented) The method of claim 33, wherein said removing comprises thinning said wafer by chemical-mechanical polishing said back surface of said wafer.

43. (Original) The method of claim 33, further comprising:
removing said adhesive from said wafer.

44. (Original) The method of claim 43, further comprising:
singulating said wafer into at least one die.

45. (Currently Amended) A method of mounting a bumped wafer having bumps on at
least a portion of a surface thereof to a wafer mounting chuck, comprising:

~~applying an adhesive having a backing to at least a portion of said bumps and at least a portion of
said surface of said wafer;~~

conforming at least a portion of said adhesive of said tape to said bumps to form a substantially
planar surface on said backing of said tape; and

mounting said wafer to said wafer mounting chuck using a suction force communicated through
said wafer mounting chuck.

46. (Canceled)

47. (Previously Presented) The method of claim 46, wherein said mounting said
wafer to said wafer mounting chuck comprises applying said suction force to at least a portion of
said substantially planar surface.

48. (Canceled)

49. (Previously Presented) The method of claim 45, wherein said mounting said
wafer to said wafer mounting chuck comprises abutting at least a portion of said backing to a
suction surface of said wafer mounting chuck.

50. (Previously Presented) The method of claim 45, wherein said wafer comprises a
wafer having a thickness of at least about 12 mils.

51. (Currently Amended) A method of using a vacuum to hold a bumped wafer
having a front surface having bumps thereon and a back surface, comprising:

applying an adhesive having a backing to at least a portion of said front surface of said wafer covering at least one bump of said bumps thereon;
conforming at least a portion of said adhesive of said tape to said bumps to form a substantially planar surface on said backing of said tape; and
holding at least a portion of said front surface of said wafer using a vacuum applied through at least a portion of a surface of a wafer mount.

52. (Canceled)

53. (Original) The method of claim 52, wherein said holding comprises applying said vacuum to said substantially planar surface of said backing.

54. (Canceled)

55. (Previously Presented) The method of claim 51, wherein said holding comprises abutting at least a portion of said backing to said surface of the wafer mount and wherein said vacuum holds said wafer to said wafer mount.

56. (Original) The method of claim 51, wherein said wafer comprises a wafer having a thickness of at least about 12 mils.

57. (Currently Amended) A wafer mount assembly for a wafer having a front surface having at least one bump thereon and a back surface, comprising:
an adhesive tape having an adhesive and a planar backing for a vacuum attachment, said adhesive tape for adhesively attaching a portion of said front surface of said wafer having said at least one bump thereon to a portion of said wafer mount assembly by said planar backing for a vacuum attachment.

58. (Previously Presented) The assembly of claim 57, further comprising:
a wafer mount having a vacuum surface thereon, said vacuum surface of said wafer mount for
abutting at least a portion of said backing of said adhesive tape, said vacuum surface
including apertures therein for communicating a vacuum therethrough.

59. (Canceled)

60. (Previously Presented) The assembly of claim 59, wherein said substantially
planar surface of said backing of said adhesive tape provides an area for the application of a
vacuum to at least a portion of said front surface of said wafer.

61. (Canceled)

62. (Previously Presented) The assembly of claim 57, wherein said adhesive attaches
to said at least one bump.

63. (Canceled)

64. (Previously Presented) The assembly of claim 57, wherein said adhesive tape
substantially overlies another bump.

65. (Previously Presented) The assembly of claim 57, wherein said wafer comprises a
wafer having a thickness of at least 12 mils.

66. (Original) The assembly of claim 57, wherein said at least one bump comprises a
conductive bump for electrical connection.

67. (Currently Amended) An assembly of a bumped wafer mounted to a wafer mount
for grinding, the assembly comprising:

a wafer having a front surface and a back surface thereof, said front surface having at least one bump thereon; and

a tape having an adhesive and a planar backing for vacuum attachment, said tape for adhesively attaching a portion of said front surface of said wafer having said at least one bump thereon.

68. (Canceled)

69. (Canceled)

70. (Canceled)

71. (Previously Presented) The assembly of claim 67, wherein said tape substantially covers said front surface of said wafer.

72. (Original) The assembly of claim 67, wherein said at least one bump comprises a conductive bump for electrical connection.

73. (Original) The assembly of claim 67, wherein said backing comprises a resilient material.

74. (Previously Presented) The assembly of claim 67, wherein said wafer comprises a thickness of at least 12 mils prior to being mounted to said wafer mount.

75. (Original) The assembly of claim 67, wherein said wafer comprises another thickness of one of about less than 6 mils and greater than about 6 mils and less than about 12 mils after grinding said back surface of said wafer.

Please add the following new claims:

76. (New) A method of attaching a wafer having bumps on a surface thereof, comprising:
attaching a tape having an adhesive and a backing on at least a portion of said surface having bumps thereon of said wafer, said tape contacting about 10% to about 60% of the surface area of said bumps;
conforming at least a portion of said adhesive of said tape to said bumps to form a substantially planar surface on said backing of said tape;
providing a wafer mount having a suction surface; and
applying a suction force to said backing of said tape.
77. (New) The method of claim 76, further comprising:
removing wafer material from a back surface of said wafer.
78. (New) The method of claim 76, wherein said applying said suction force to said backing of said tape comprises applying a suction force to said substantially planar surface of said backing.
79. (New) The method of claim 76, wherein said applying a suction force to said backing of said tape includes abutting said backing to said suction surface of said wafer mount.
80. (New) The method of claim 76, wherein said wafer comprises a wafer having a thickness of at least about 12 mils.
81. (New) The method of claim 77, wherein said removing comprises thinning said wafer to a thickness in the range of between about 6 mils and about 12 mils.

82. (New) The method of claim 77, wherein said removing comprises thinning said wafer to one of about 6 mils thickness and less than about 6 mils thickness.

83. (New) The method of claim 77, wherein said removing comprises grinding said back surface of said wafer.

84. (New) The method of claim 77, wherein said removing comprises thinning said wafer by chemical-mechanical polishing said back surface of said wafer.